



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China

MPI4040

High current, high frequency, miniature power inductors



Description

- Handles high transient inrush current spikes
- Magnetically shielded
- Frequency range 20kHz to 10MHz
- Inductance range from 0.10µH to 22µH
- Current range from 1.1 A to 32.0 A
- 4.7 x 4.31 footprint surface mount package in 1.2, 1.5, 1.85 or 2.0mm heights
- Rugged construction
- Halogen free, lead free, RoHS compliant

Applications

- Handheld/mobile devices
- Portable media players
- GPS/PDAs
- MP3 Players
- Battery operated devices
- Notebook/netbook/laptop
- Tablets/smartphones
- LCD Displays
- LED Drivers
- FOL Converters

Environmental Data

- Storage temperature range (component): -55°C to +125°C
- Operating temperature range: -55°C to +125°C (Ambient plus self temperature rise)
- Solder reflow temperature: J-STD-020D compliant



Product Specifications

Part Number ⁵	OCL ¹ ± 20% (μH)	Part marking designator	I _{rms} ² (amps)	I _{sat} ³ @ 25°C (amps)	DCR (mΩ) ±20% @ 20°C	K-factor ⁴
R1 — 1.2mm Height						
MPI4040R1-R10-R	0.10	A	8.0	32 [†]	8.5	1401
MPI4040R1-R15-R	0.15	B	7.0	26 [†]	11	989
MPI4040R1-R22-R	0.23	C	5.5	21	18	814
MPI4040R1-R33-R	0.33	D	4.4	17	28	659
MPI4040R1-R47-R	0.47	E	5.2	11.5	20	1295
MPI4040R1-R68-R	0.68	F	3.3	9.0	51	461
MPI4040R1-1R0-R	1.0	G	3.7	7.7	40	990
MPI4040R1-1R5-R	1.5	H	3.0	6.5	60	732
MPI4040R1-2R2-R	2.2	I	2.6	5.9	80	623
MPI4040R1-3R3-R	3.3	J	2.2	5.1	115	481
MPI4040R1-4R7-R	4.7	K	1.8	3.8	180	411
MPI4040R1-6R8-R ^{††}	6.8	L	1.5	2.2	250	344
MPI4040R1-100-R ^{††}	10	M	1.2	2.8	370	276
R2 — 1.5mm Height						
MPI4040R2-R47-R	0.47	A	6.4	12.2	13	1403
MPI4040R2-1R0-R	1.0	B	4.6	8.9	25	935
MPI4040R2-1R5-R	1.5	C	3.8	7.6	37	701
MPI4040R2-2R2-R	2.2	D	3.1	5.7	58	647
MPI4040R2-3R3-R	3.3	E	2.6	5.4	76	495
MPI4040R2-4R7-R	4.7	F	2.1	4.3	115	421
MPI4040R2-6R8-R	6.8	G	1.8	3.4	158	351
MPI4040R2-100-R ^{††}	10.0	H	1.5	3.1	240	271

1. Open Circuit Inductance (OCL) test 200kHz, 0.10V_{pp}, 0.0Adc

2. I_{rms}: DC current for an approximate 10°C temperature rise of 40°C without core loss. Line rating is necessary for AC currents.

Temperature rise is dependent upon several factors, including line, PCB pad layout, trace thickness and width, air-flow and proximity to other heat generating components. It is recommended the part temperature not exceed 125°C under worst case operating conditions and therefore, the temperature rise should be verified in the end user application. I_{rms} testing was performed on a 19.05mm long x 6.35mm wide x 0.070mm thick copper core; it is still air.

3. I_{sat}[†]: Peak current for approximately 30% roll-off at +25°C.

4. K-factor Used to determine B_{pp} for core loss (see graph).

$$B_{pp} = K * L * DI.B_{pp} : (\text{Gauss}), K: (\text{K-factor from table}), L: (\text{inductance in } \mu\text{H}),$$

DI = (peak-to-peak ripple current in amps).

5. Part Number Definition: MPI4040R-XXX-R

- MPI4040R = product code and size
- X = version indicator
- XXX = inductance value in μH, R= decimal point - If no R is present, then last character equals the number of zeros
- -R suffix = RoHS compliant

† Transient pulse not to exceed 1 millisecond.

†† Maximum operating frequency less than 10MHz, consult factory for application specific values.

Product Specifications

Part Number ⁵	OCL ¹ ± 20% (µH)	Part marking designator	I _{ms} ² (amps)	I _{sat} ³ @ 25°C (amps)	DCR (mΩ) ±20% @ 20°C	K-factor ⁴
R3 — 1.85mm Height						
MPI4040R3-R22-R	0.22	A	8.0	20	5.8	1870
MPI4040R3-R47-R	0.47	B	5.8	17	10.3	1530
MPI4040R3-1R2-R	1.2	C	4.0	9.4	32	732
MPI4040R3-1R5-R	1.5	D	3.8	8.2	36	673
MPI4040R3-2R2-R	2.2	E	3.4	7.9	48	543
MPI4040R3-3R3-R	3.3	F	3.0	6.6	60	432
MPI4040R3-4R7-R	4.7	G	2.3	4.8	92	374
MPI4040R3-6R8-R	6.8	H	2.0	4.5	120	306
MPI4040R3-100-R	10	I	1.5	3.8	213	251
MPI4040R3-150-R	15	J	1.3	3.0	285	213
MPI4040R3-220-R ^{††}	22	K	1.1	2.2	408	174
R4 — 2.0mm Height						
MPI4040R4-R22-R	0.22	A	10.1	15	5.3	2405
MPI4040R4-R33-R	0.33	B	9.5	12.8	6.0	1870
MPI4040R4-R47-R	0.45	C	8.1	11.5	8.2	1530
MPI4040R4-1R0-R	1.0	D	5.7	8.2	17	900
MPI4040R4-1R5-R	1.5	E	4.9	6.9	23	802
MPI4040R4-2R2-R	2.2	F	3.9	5.7	35	673
MPI4040R4-3R3-R ^{††}	3.3	G	3.3	4.5	40	510
MPI4040R4-4R7-R ^{††}	4.7	H	2.9	3.9	67	455
MPI4040R4-6R8-R ^{††}	6.8	I	2.4	3.2	91	374
MPI4040R4-100-R ^{††}	10	J	1.9	2.6	148	306
MPI4040R4-220-R ^{††}	22	K	1.3	1.8	316	203

1. Open Circuit Inductance (OCL) Test Parameters: 100% L₁, 0.17V_d, < 0.1Adc

2. I_{ms}: DC current for an approximate temperature rise of 4 °C without core loss. De-rating is necessary for AC currents. Temperature rise is dependent upon several factors, including the PCB pad layout, trace thickness and width, air-flow and proximity to other heat generating components. It is recommended the part temperature not exceed 125°C under worst case operating conditions and therefore, the temperature rise should be verified in the end use application. I_{ms} testing was performed on a 9.05mm long x 6.35mm wide x 0.70 mm thick copper trace in still air.

3. I_{sat}: Peak current for approximately 30% rolloff at +25 °C.

4. K-factor: Used to determine B_{pp} for core loss (see graph).

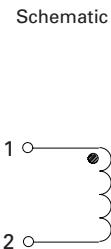
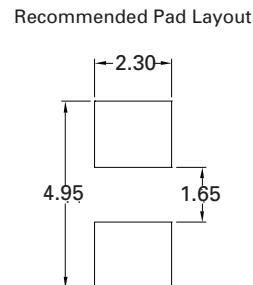
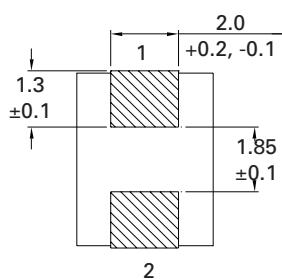
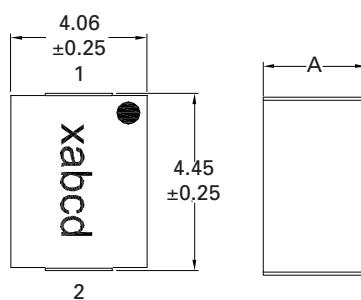
$$B_{pp} = K * L * D(L)B_{pp} : (\text{Gauss}), K: (\text{K-factor from table}), L: (\text{inductance in } \mu\text{H}), D(L) = (\text{peak-to-peak ripple current in amps}).$$

5. Part Number Definition: MPI4040R-XXX-R

- MPI4040R = product code and size
- X = version indicator
- XXX = inductance value in µH, R= decimal point - If no R is present, then last character equals the number of zeros
- -R suffix = RoHS compliant

† Transient pulse not to exceed 1 millisecond.

†† Maximum operating frequency less than 10MHz, consult factory for application specific values.

Dimensions (mm)

Part number	A Max
MPI4040R1-xxx-R	1.2
MPI4040R2-xxx-R	1.5
MPI4040R3-xxx-R	1.8
MPI4040R4-xxx-R	2.0

Part marking: xabcd

x = height: 1 = R1 (1.2mm), 2 = R2 (1.5mm), 3 = R3 (1.85mm), 4 = R4 (2.0mm)

a = Inductance value per the Part marking designator letter code in Product specification table.

b = Bi-weekly date code

c = Last digit of year manufactured

d = Revision level

Soldering surfaces to be coplanar within 0.10 millimeters
 PCB tolerances are ± 0.1 millimeters unless stated otherwise
 Do not route traces or vias underneath the inductor

Packaging information (mm)

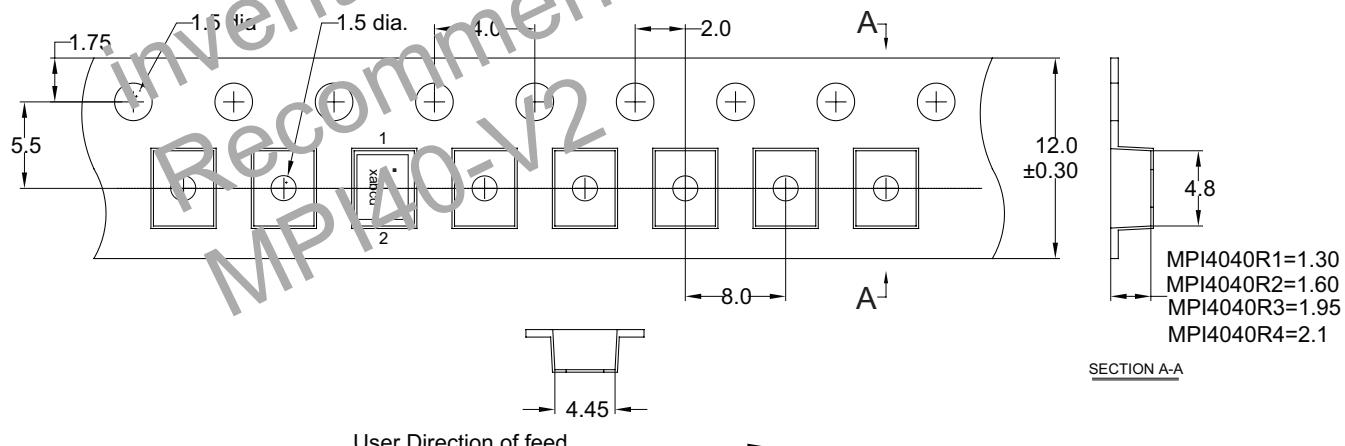
Supplied in tape and reel packaging:

MPI4040R1 = 5100 parts per 13" diameter reel

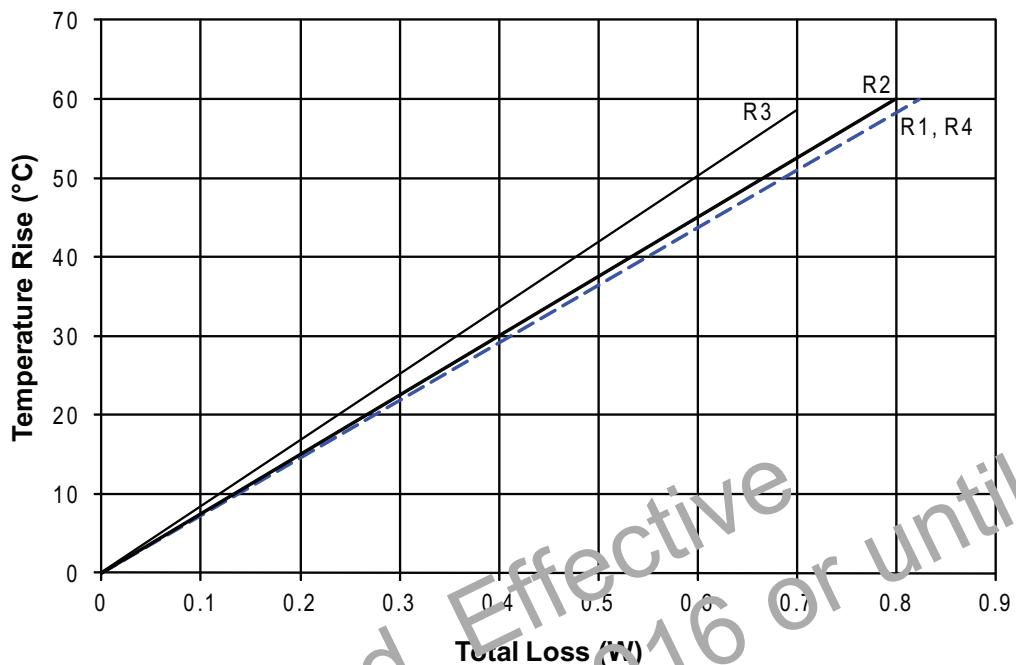
MPI4040R2 = 4500 parts per 13" diameter reel

MPI4040R3 = 3500 parts per 13" diameter reel

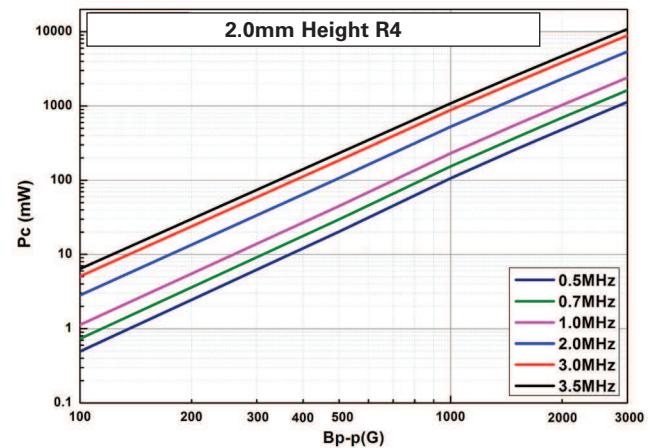
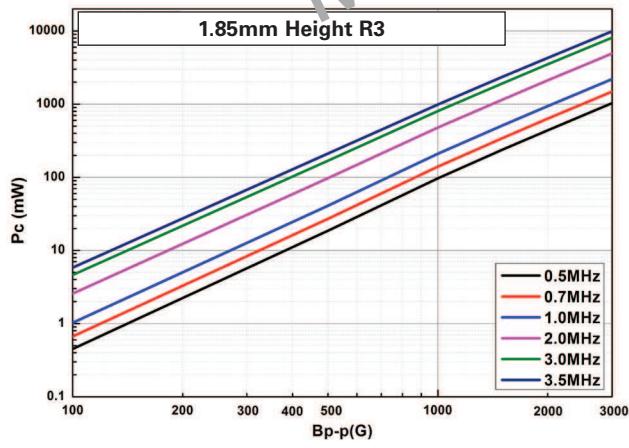
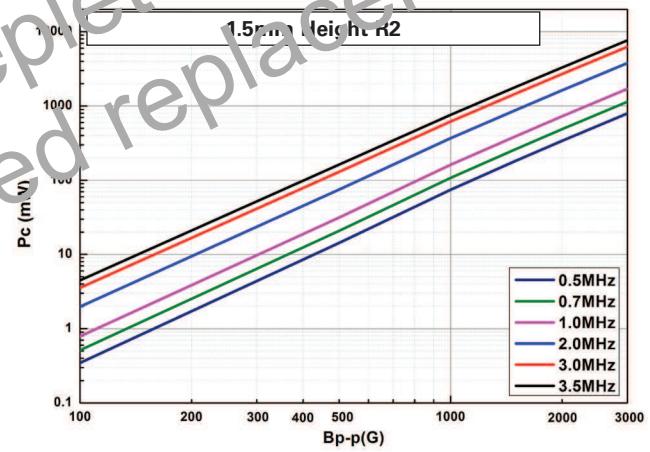
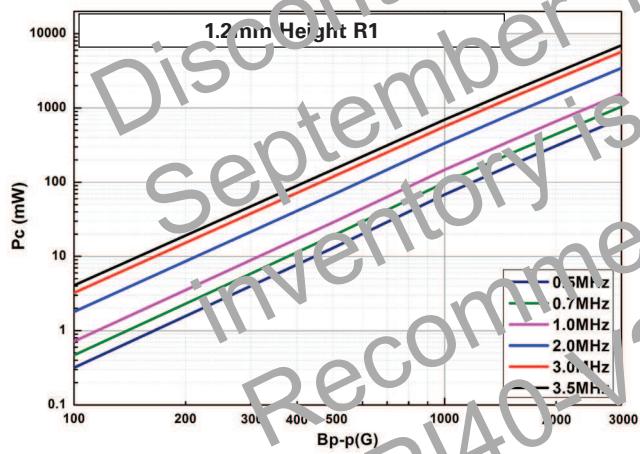
MPI4040R4 = 3000 parts per 13" diameter reel



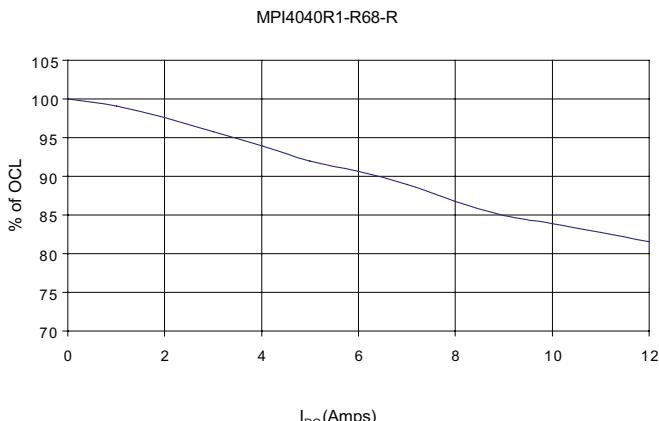
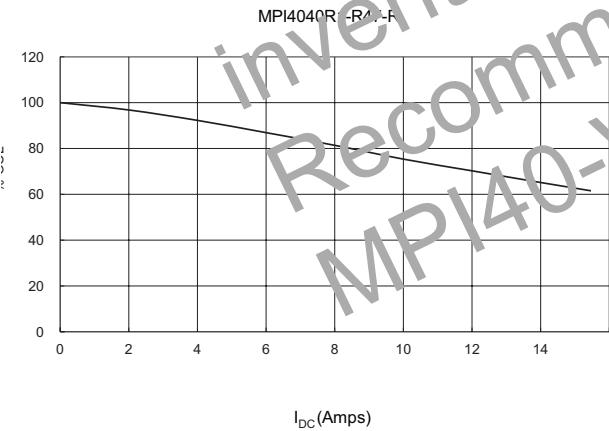
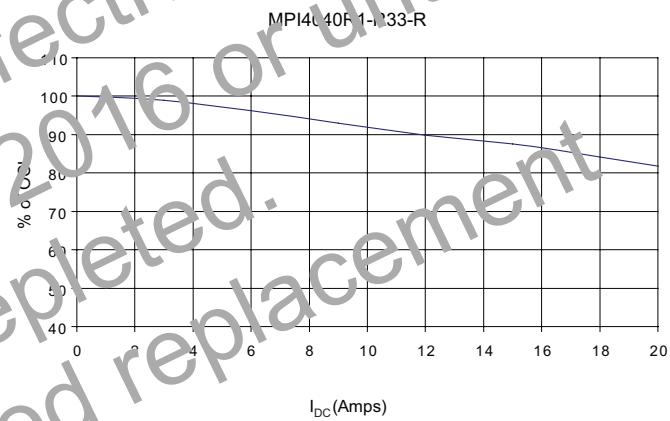
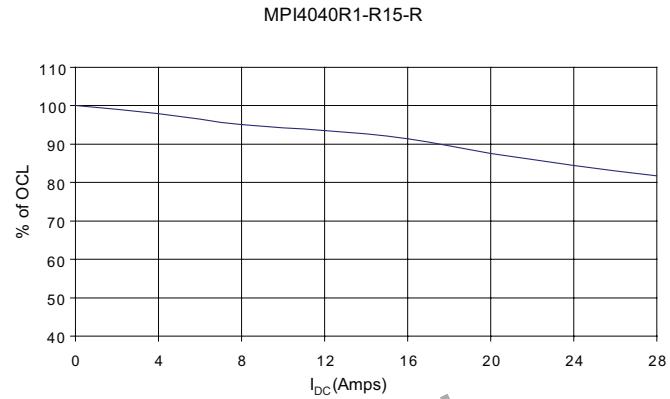
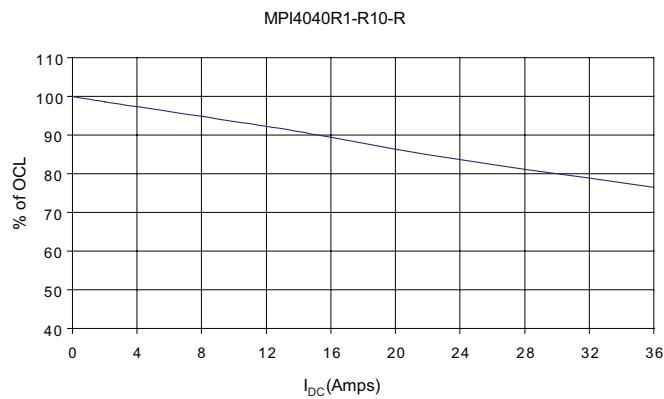
Temperature rise vs. total loss

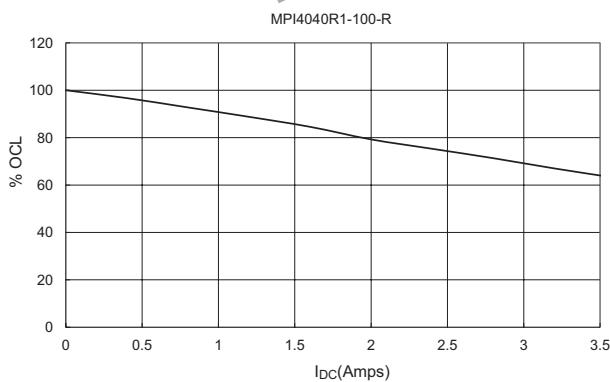
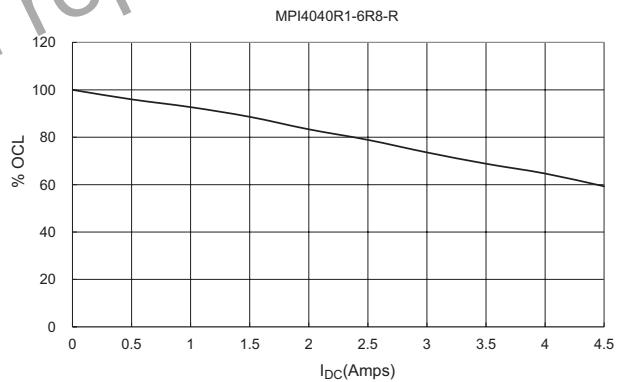
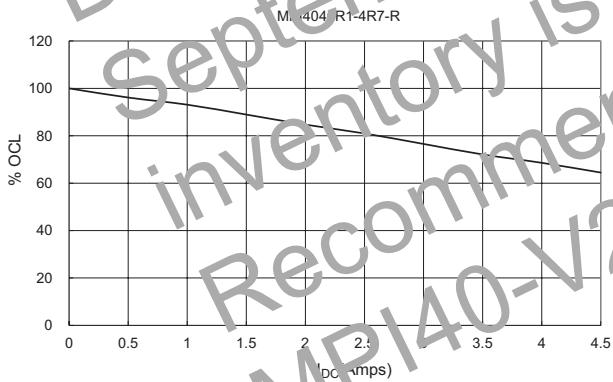
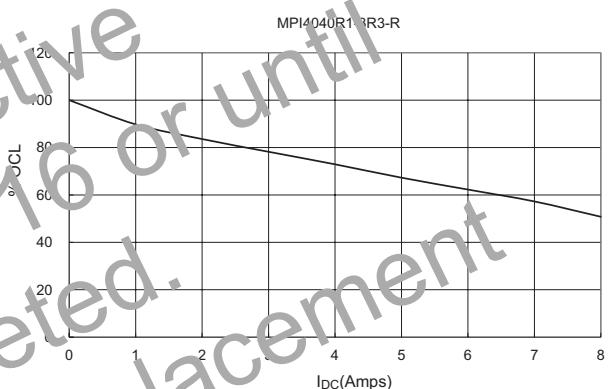
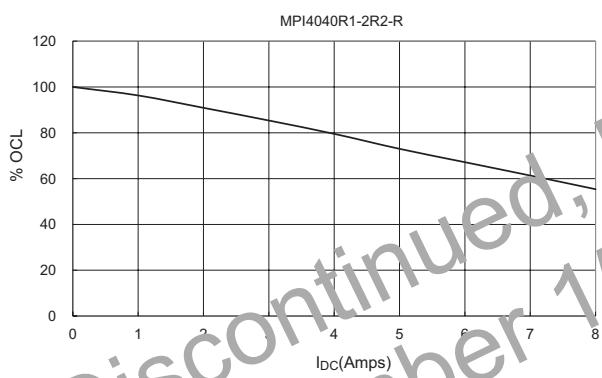
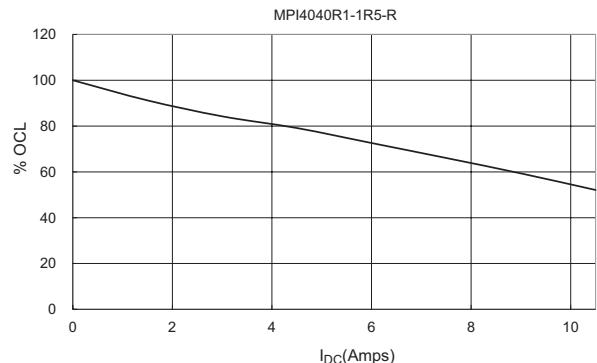
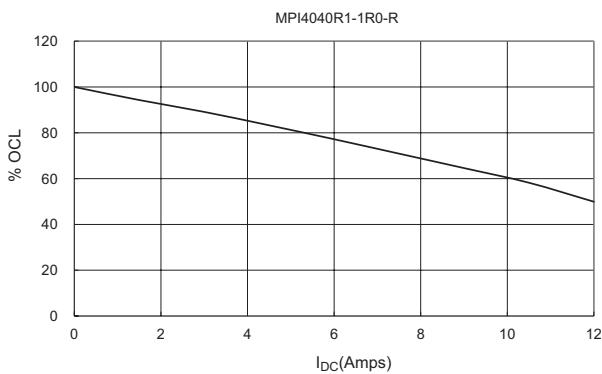


Core loss



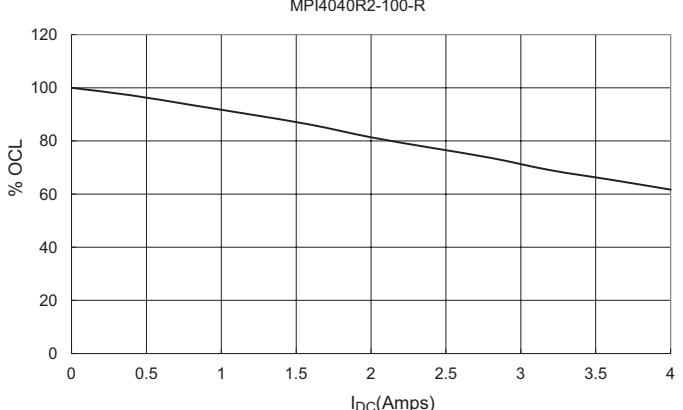
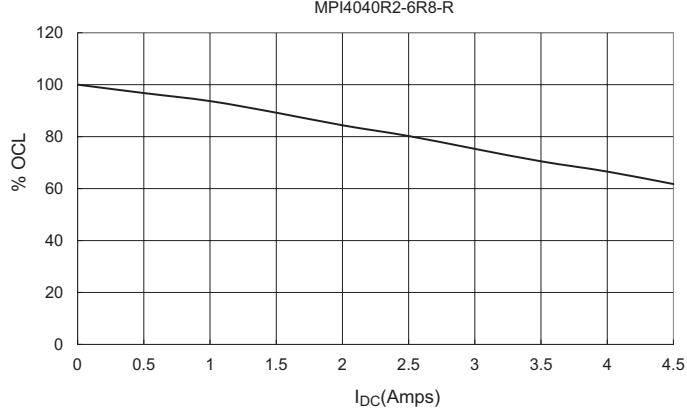
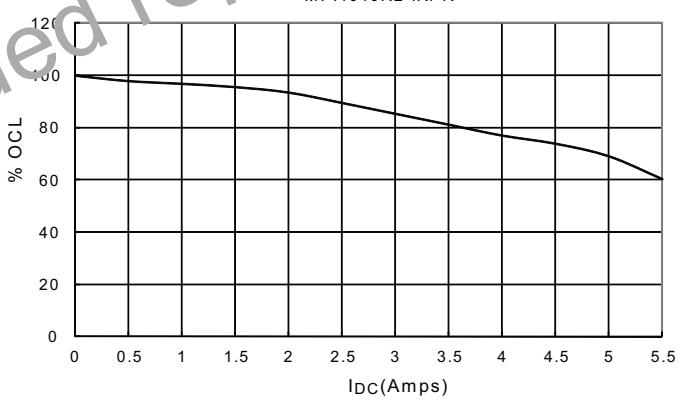
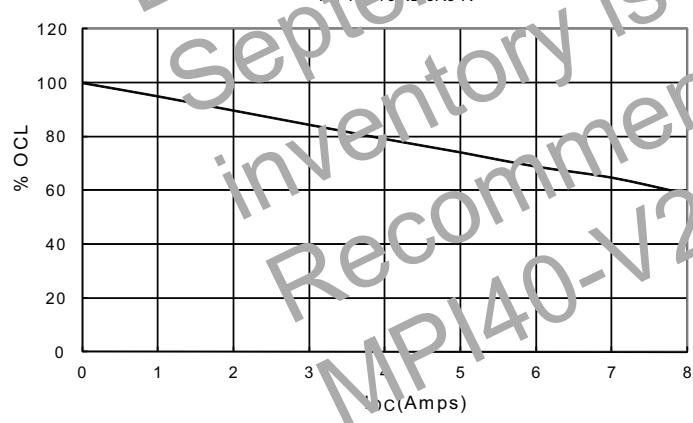
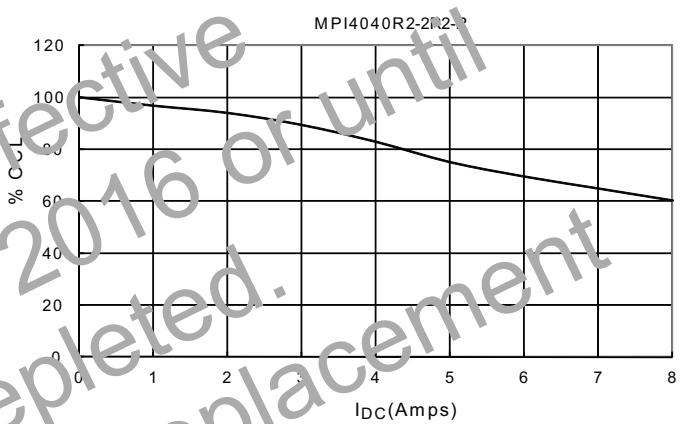
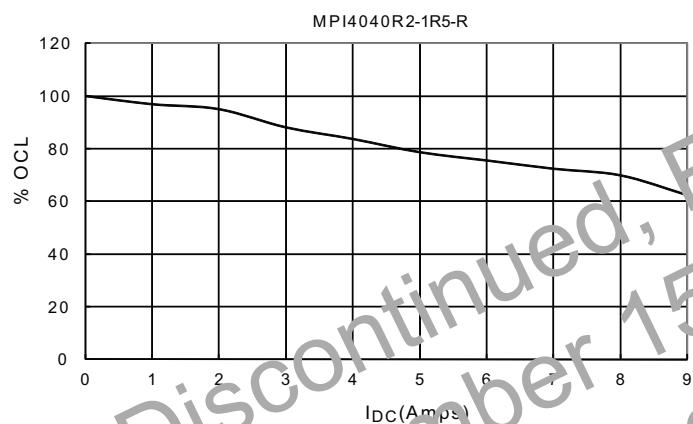
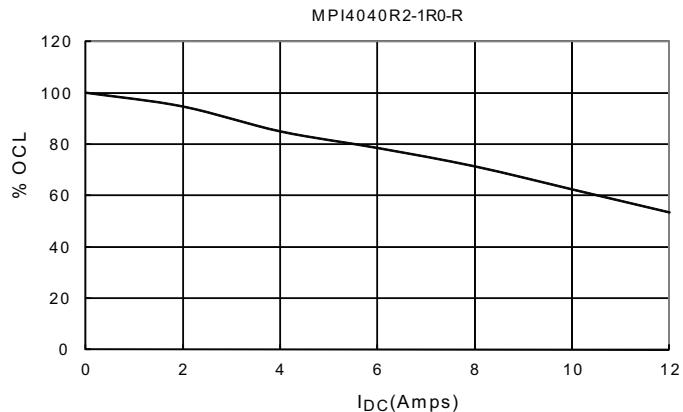
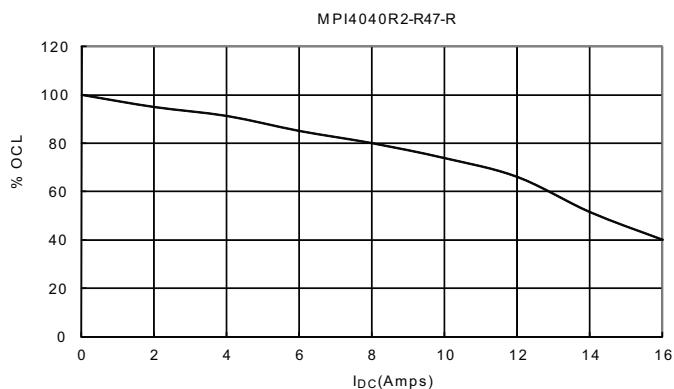
1.2mm Height R1 inductance characteristics — % of OCL vs. I_{DC}

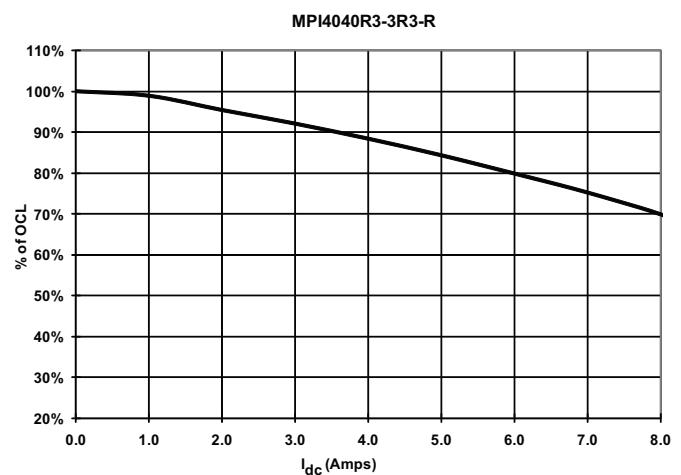
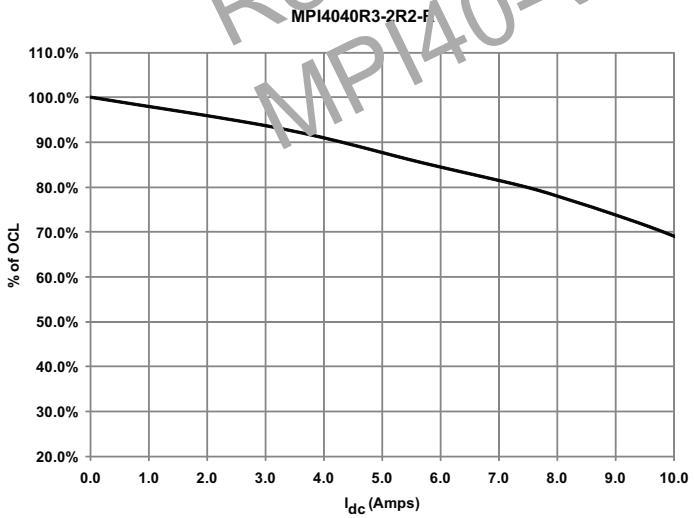
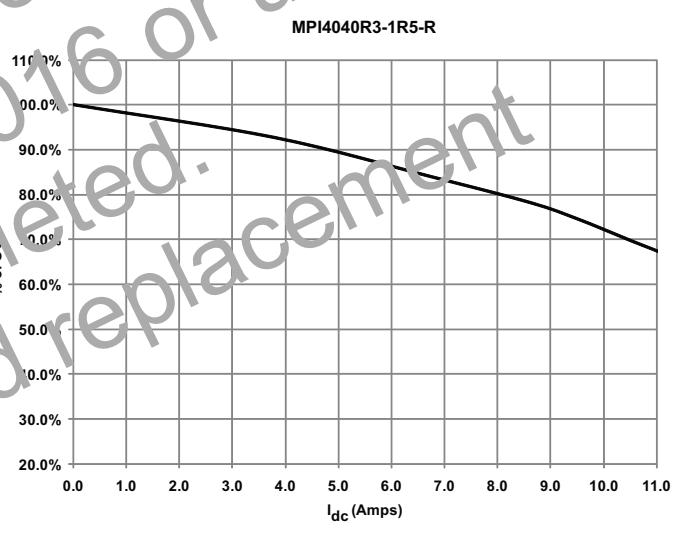
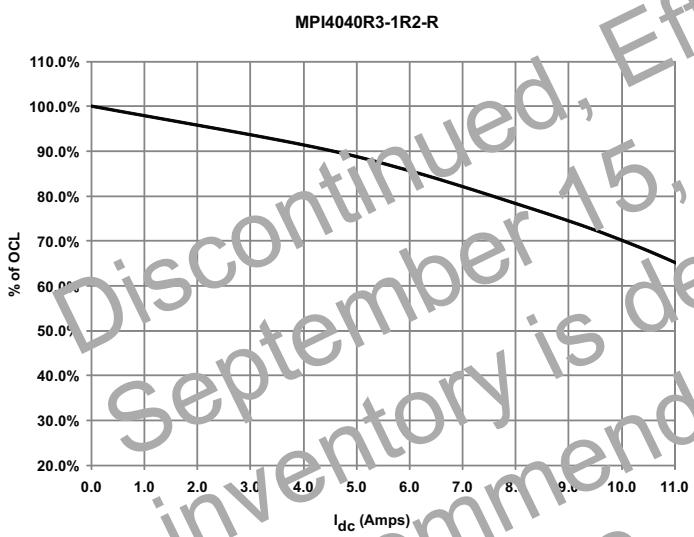
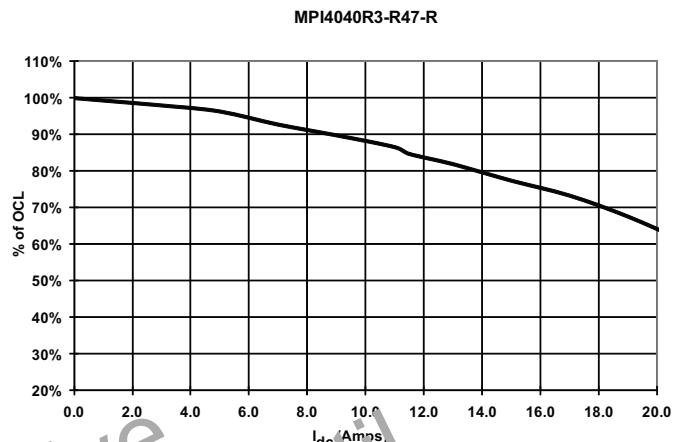
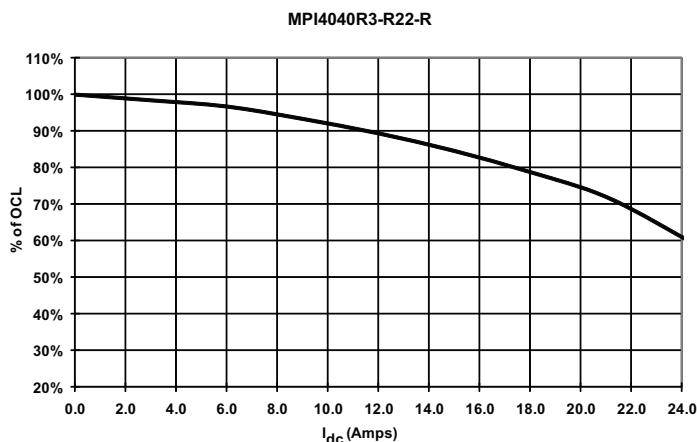


1.2mm Height R1 inductance characteristics — % of OCL vs. I_{DC} 

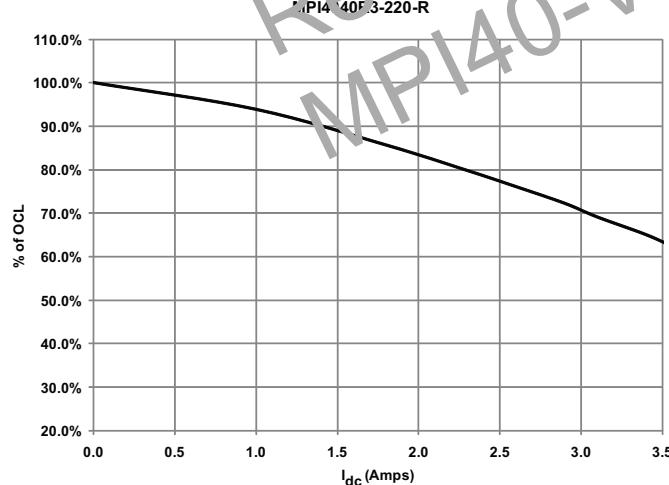
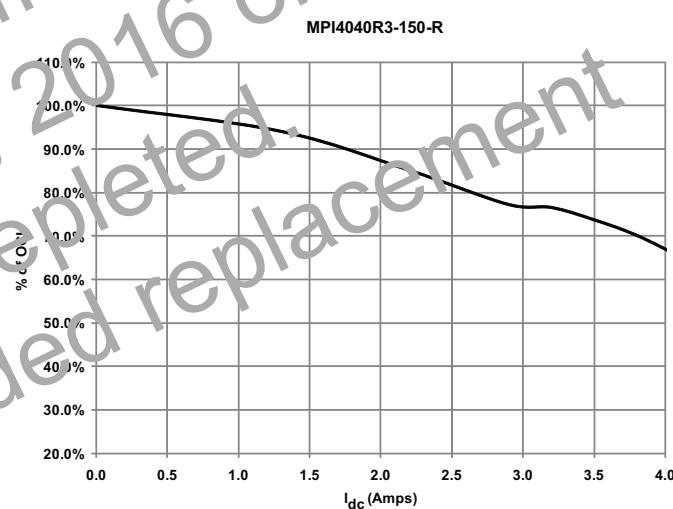
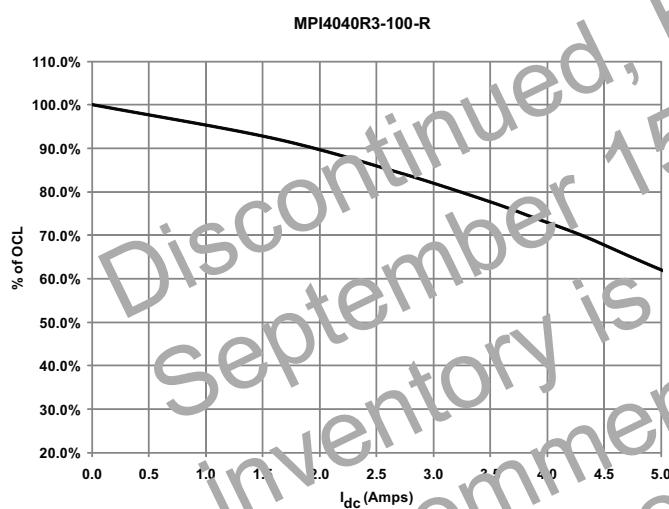
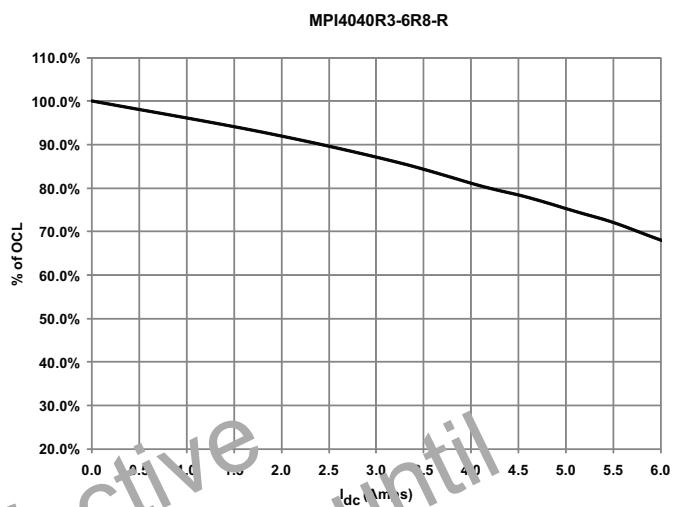
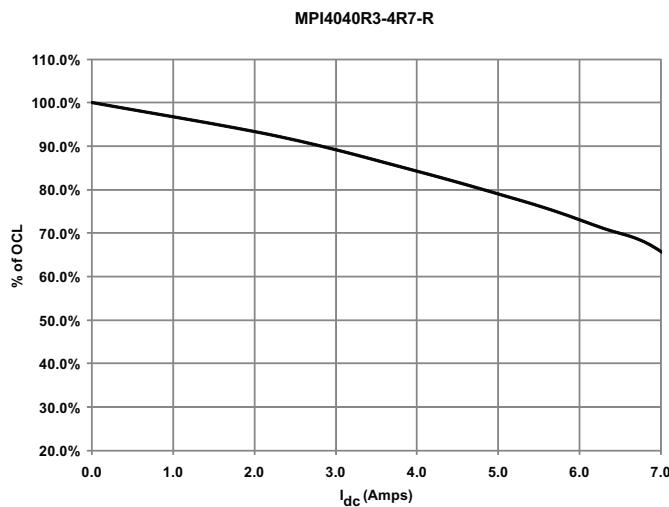
Discontinued, Effective September 15, 2016 or until inventory is depleted. Recommended replacement: MPI40-V2

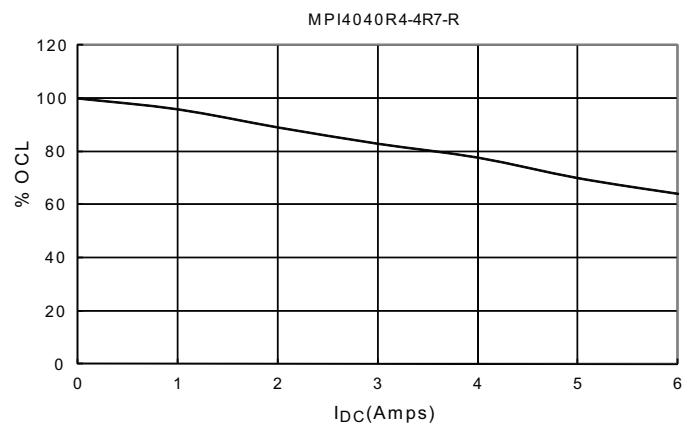
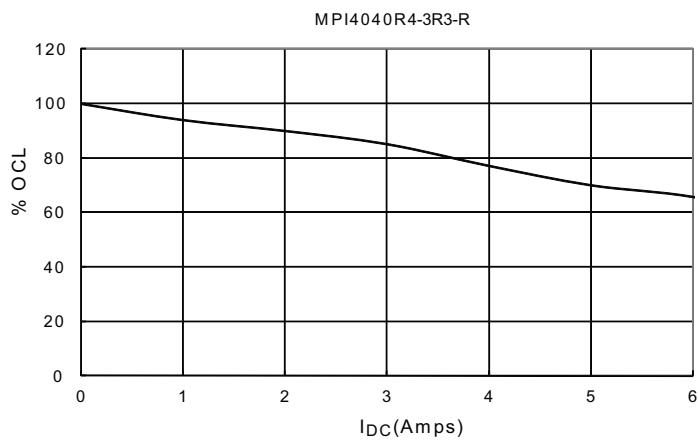
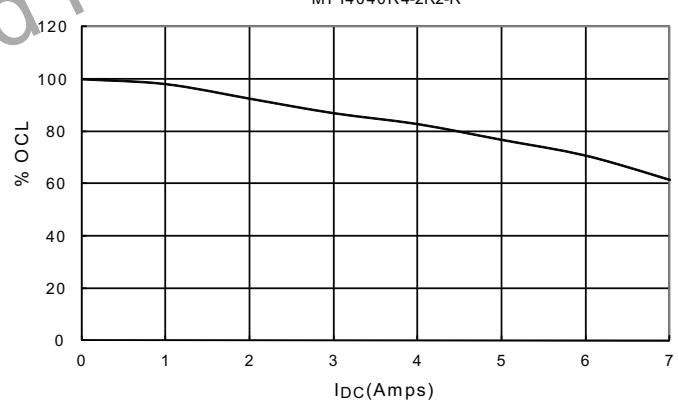
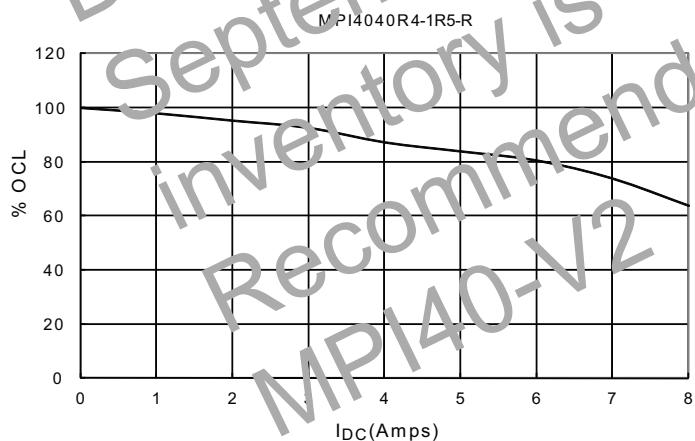
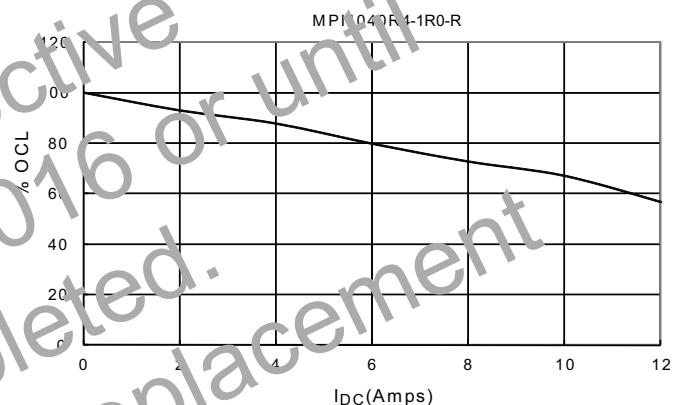
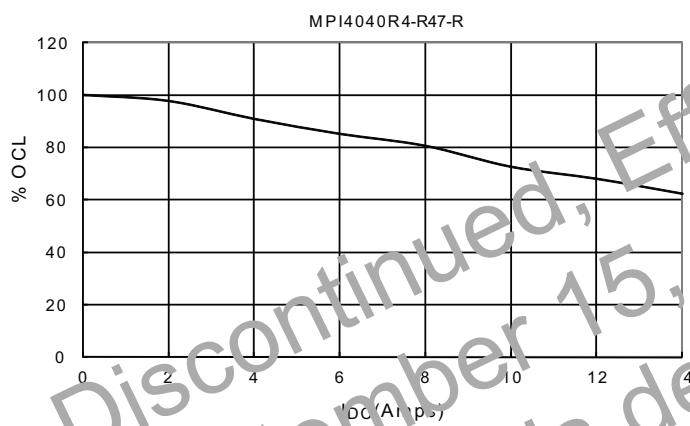
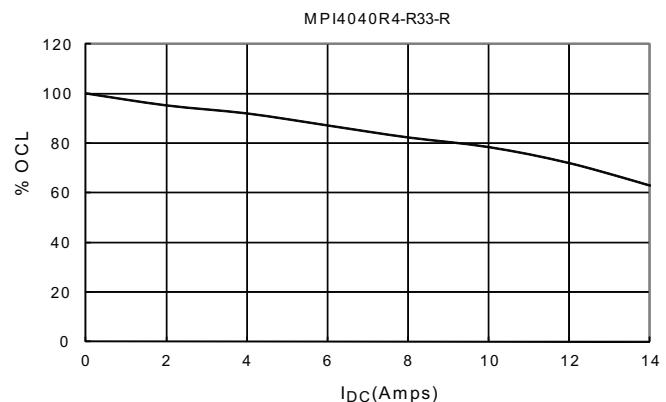
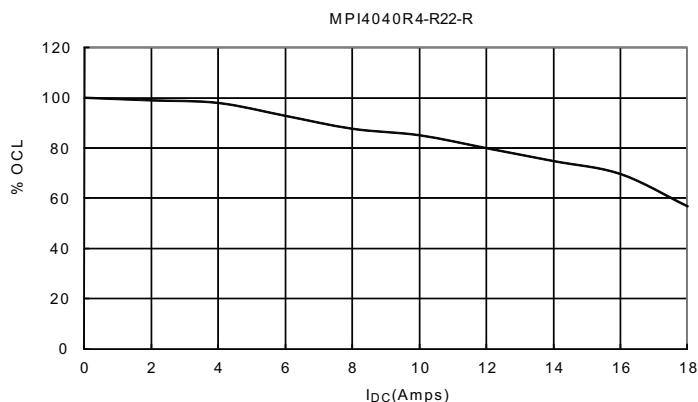
1.5mm Height R2 inductance characteristics — % of OCL vs. I_{DC}



1.85mm Height R3 inductance characteristics — % of OCL vs. I_{DC} 

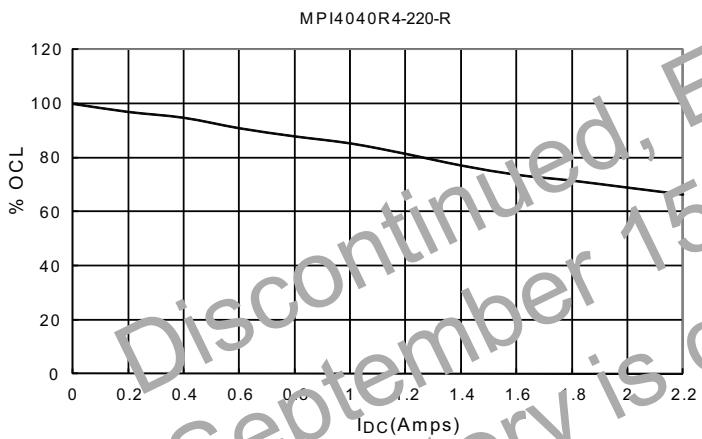
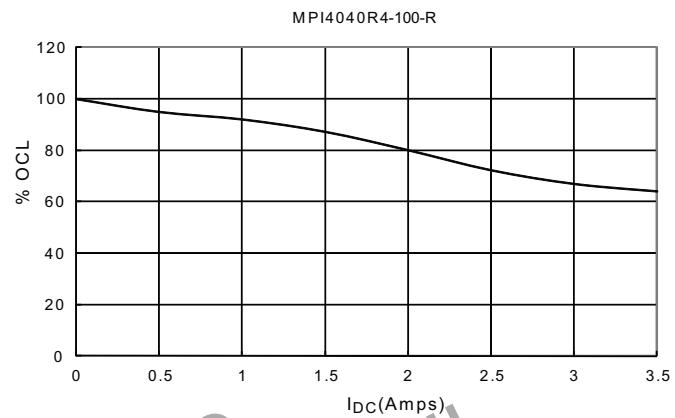
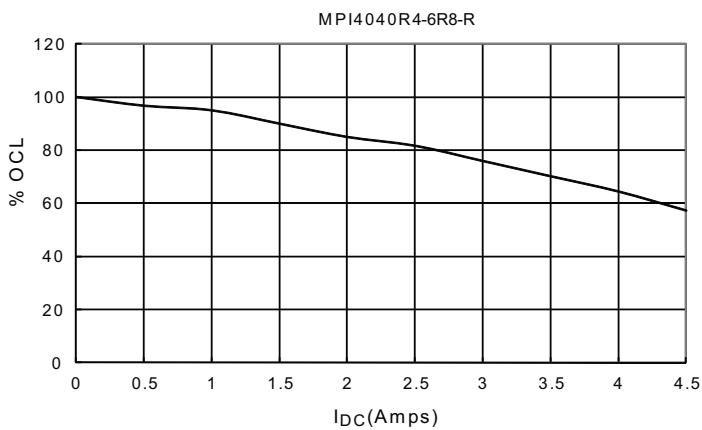
1.85mm Height R3 inductance characteristics — % of OCL vs. I_{dc}



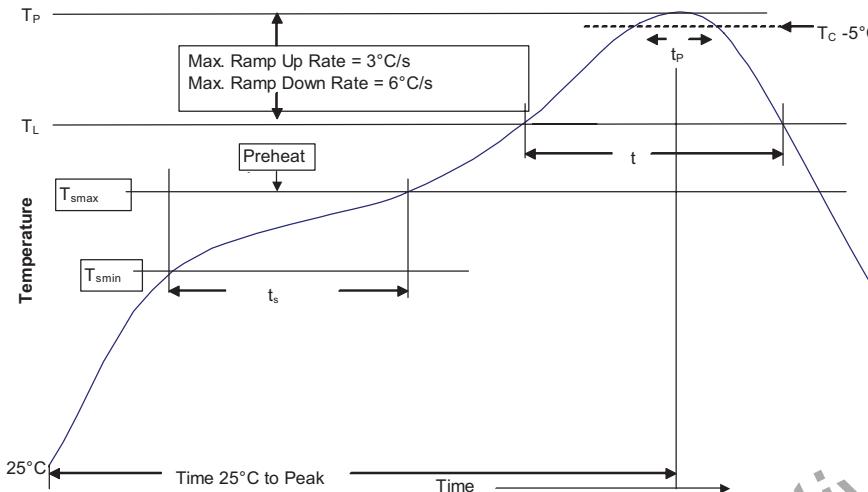
2.0mm Height R4 inductance characteristics — % of OCL vs. I_{DC} 

Discontinued, September 15, 2016 or until inventory is depleted. Recommended replacement: MPI40-V2

2.0mm Height R4 inductance characteristics – % of OCL vs. I_{DC}



Discontinued, Effective
September 15, 2016 or until
inventory is depleted.
Recommended replacement
MPI40-V2

Solder reflow profile**Table 1 - Standard SnPb Solder (T_c)**

Package Thickness	Volume mm ³ <350	Volume mm ³ ≥350
<2.5mm)	235°C	220°C
≥2.5mm	220°C	220°C

Table 2 - Lead (Pb) Free Solder (T_c)

Package Thickness	Volume mm ³ <350	Volume mm ³ 350 - 2000	Volume mm ³ >2000
<1.6mm	260°C	260°C	260°C
1.6 – 2.5mm	260°C	250°C	245°C
>2.5mm	250°C	245°C	245°C

Reference JDEC J-STD-020D

Profile Feature	Standard SnPb Solder	Lead (Pb) Free Solder
Preheat and Soak	<ul style="list-style-type: none"> Temperature min. (T_{smin}) Temperature max. (T_{smax}) Time (T_{smin} to T_{smax}) (t_s) 	<ul style="list-style-type: none"> 100°C 150°C 60-120 Seconds
Average ramp up rate T_{smax} to T_p	3°C/ Second Max.	3°C/ Second Max.
Liquidus temperature (T_L)	83°C	217°C
Time at liquidous (t_L)	6-150 Seconds	60-150 Seconds
Peak package body temperature (T_p)*	Table 1	Table 2
Time (t_p)** within 5 °C of the specified classification temperature (T_c)	20 Seconds**	30 Seconds**
Average ram-down rate (T_p to T_{smax})	5°C/ Second Max.	6°C/ Second Max.
Time 25°C to Peak Temperature	6 Minutes Max.	8 Minutes Max.

* Tolerance for peak profile temperature (T_p) is defined as a supplier minimum and a user maximum.

** Tolerance for time at peak profile temperature (t_p) is defined as a supplier minimum and a user maximum.

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